



SOT618-11

HVQFN40, plastic, thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.9 mm body

13 August 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220 VJJD-2
Mounting method type	S (surface mount)
Issue date	03-11-2016
Manufacturer package code	98ASA10655D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

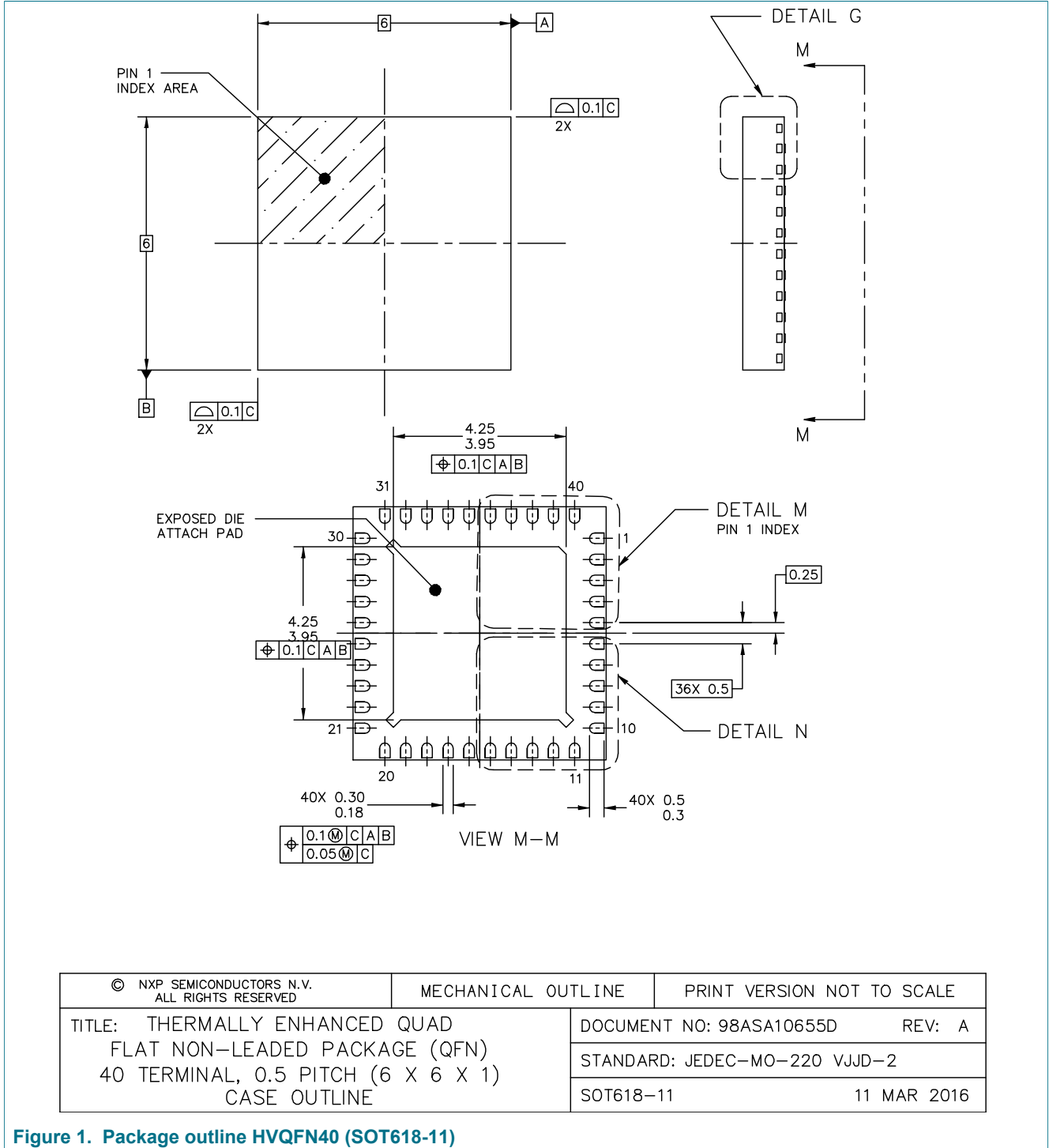


Figure 1. Package outline HVQFN40 (SOT618-11)

HVQFN40, plastic, thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.9 mm body

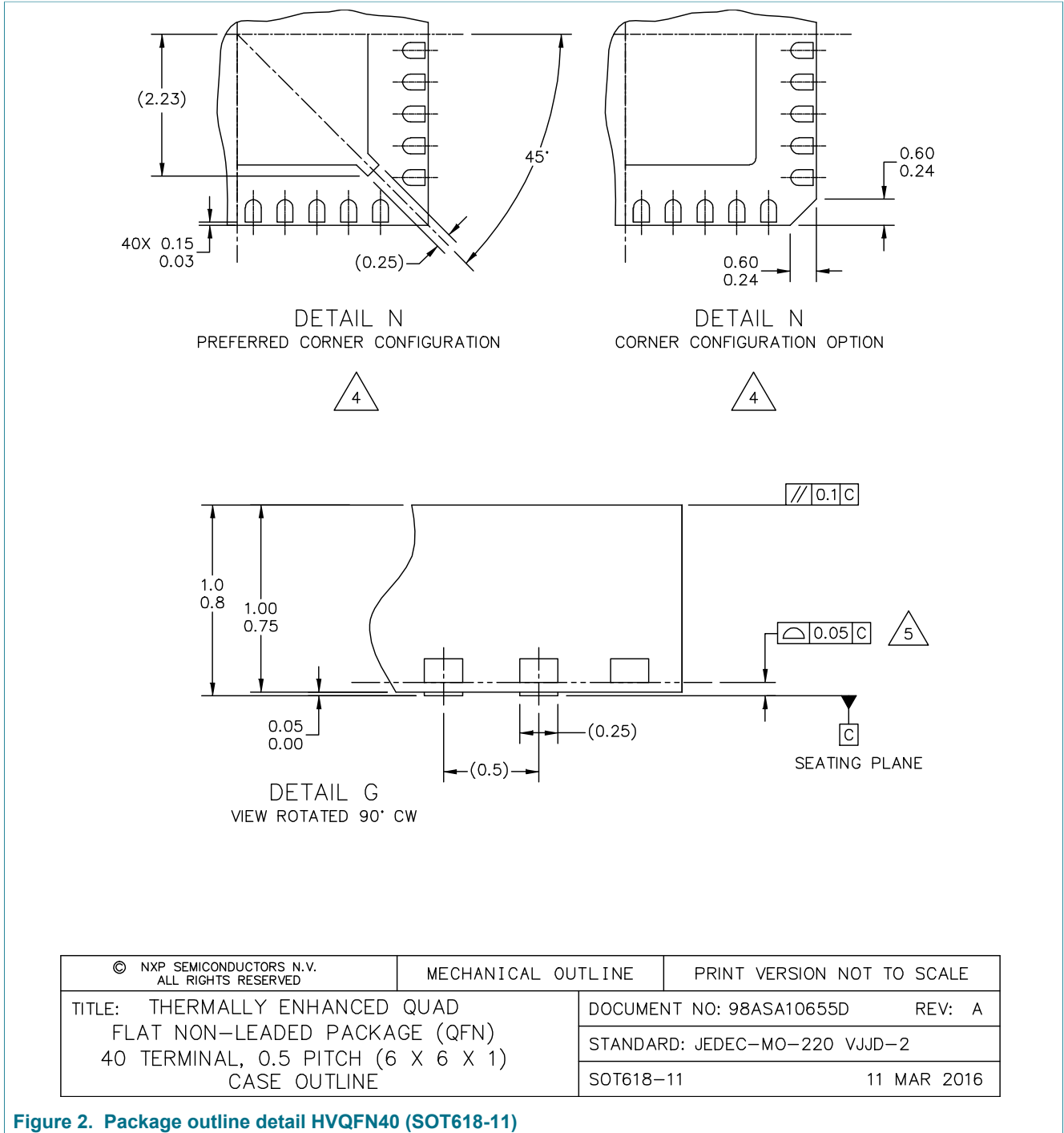


Figure 2. Package outline detail HVQFN40 (SOT618-11)

HVQFN40, plastic, thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.9 mm body

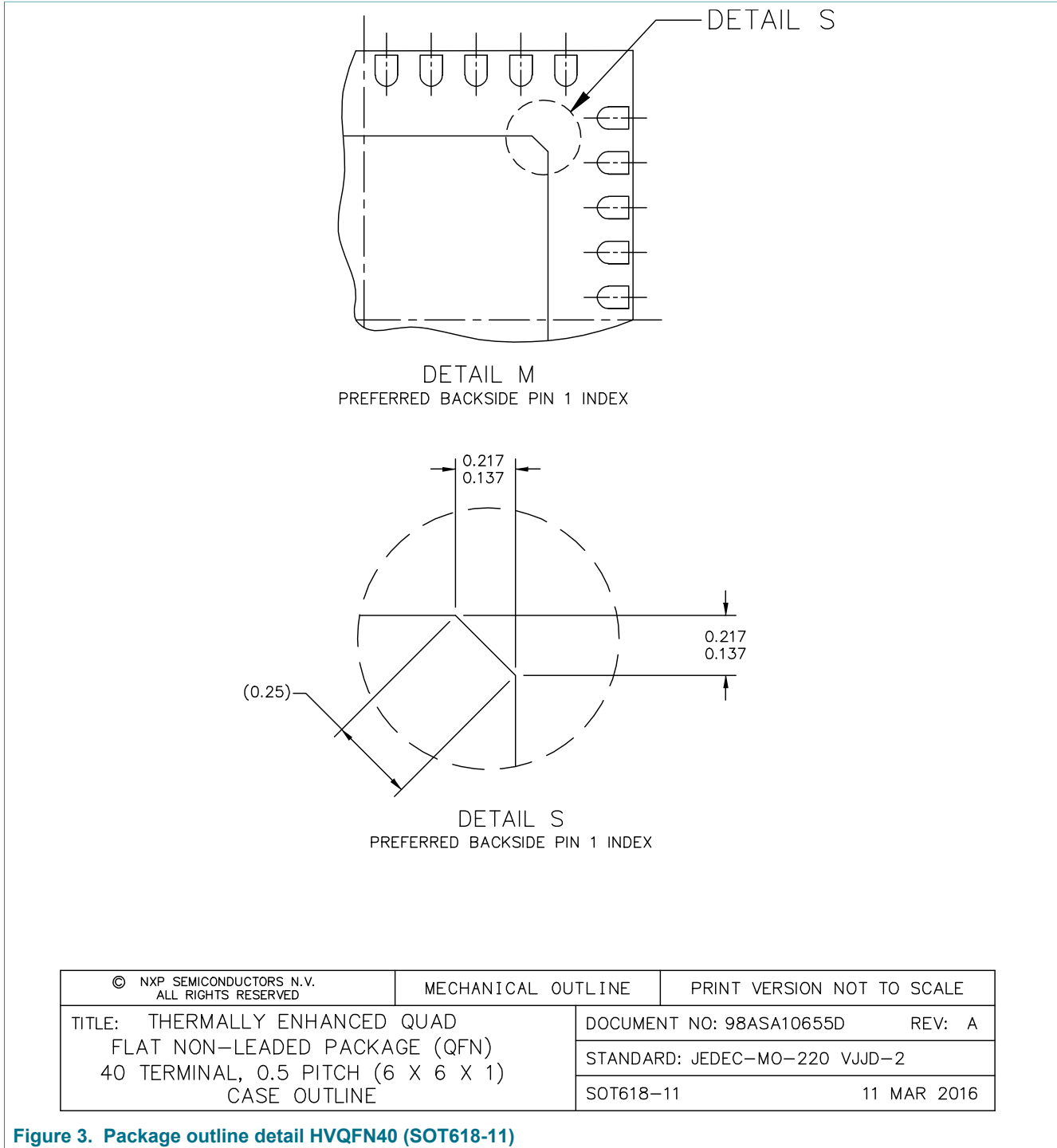


Figure 3. Package outline detail HVQFN40 (SOT618-11)

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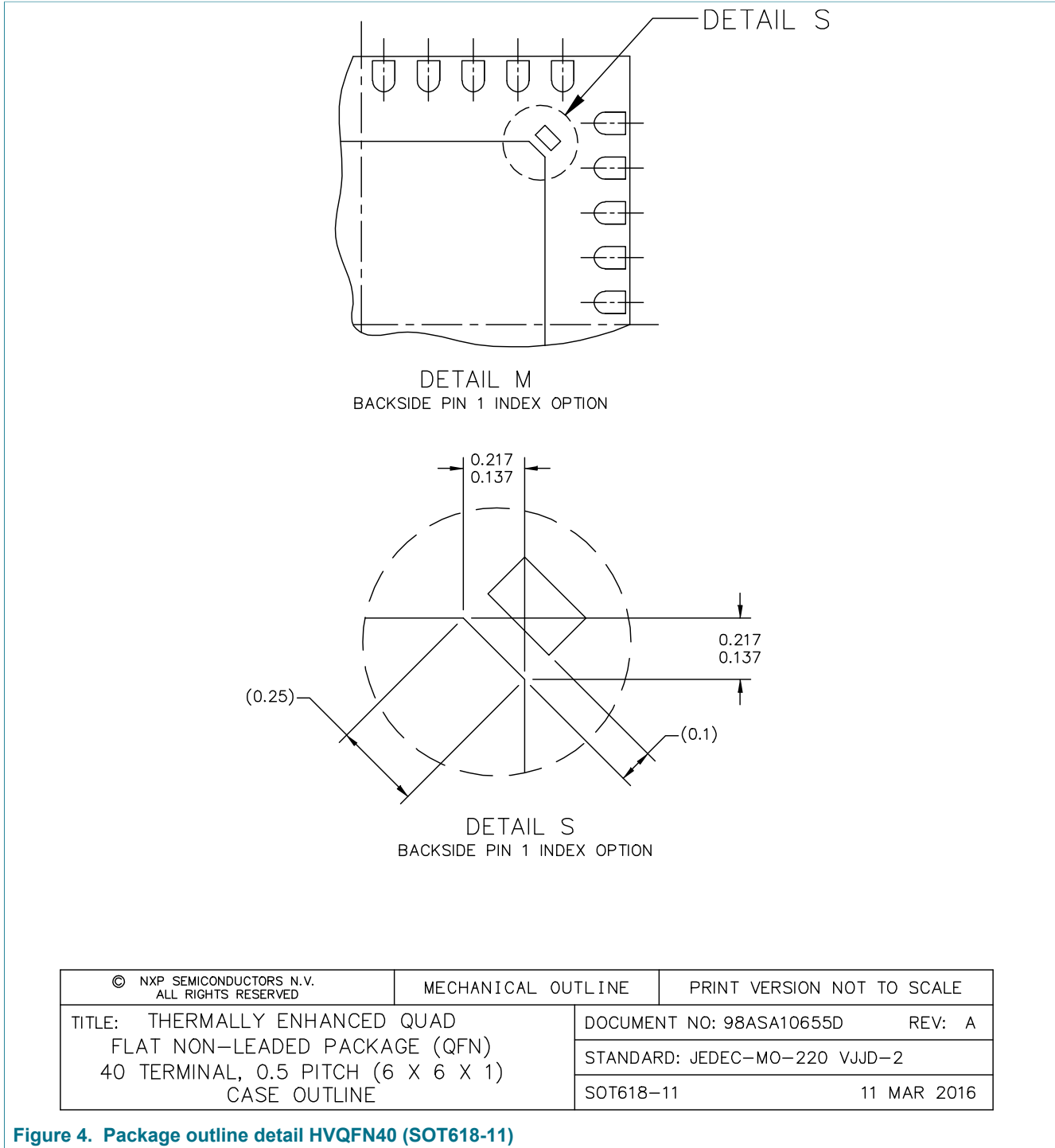


Figure 4. Package outline detail HVQFN40 (SOT618-11)

HVQFN40, plastic, thermal enhanced very thin quad flat package; no leads; 40 terminals; 0.5 mm pitch; 6 mm x 6 mm x 0.9 mm body

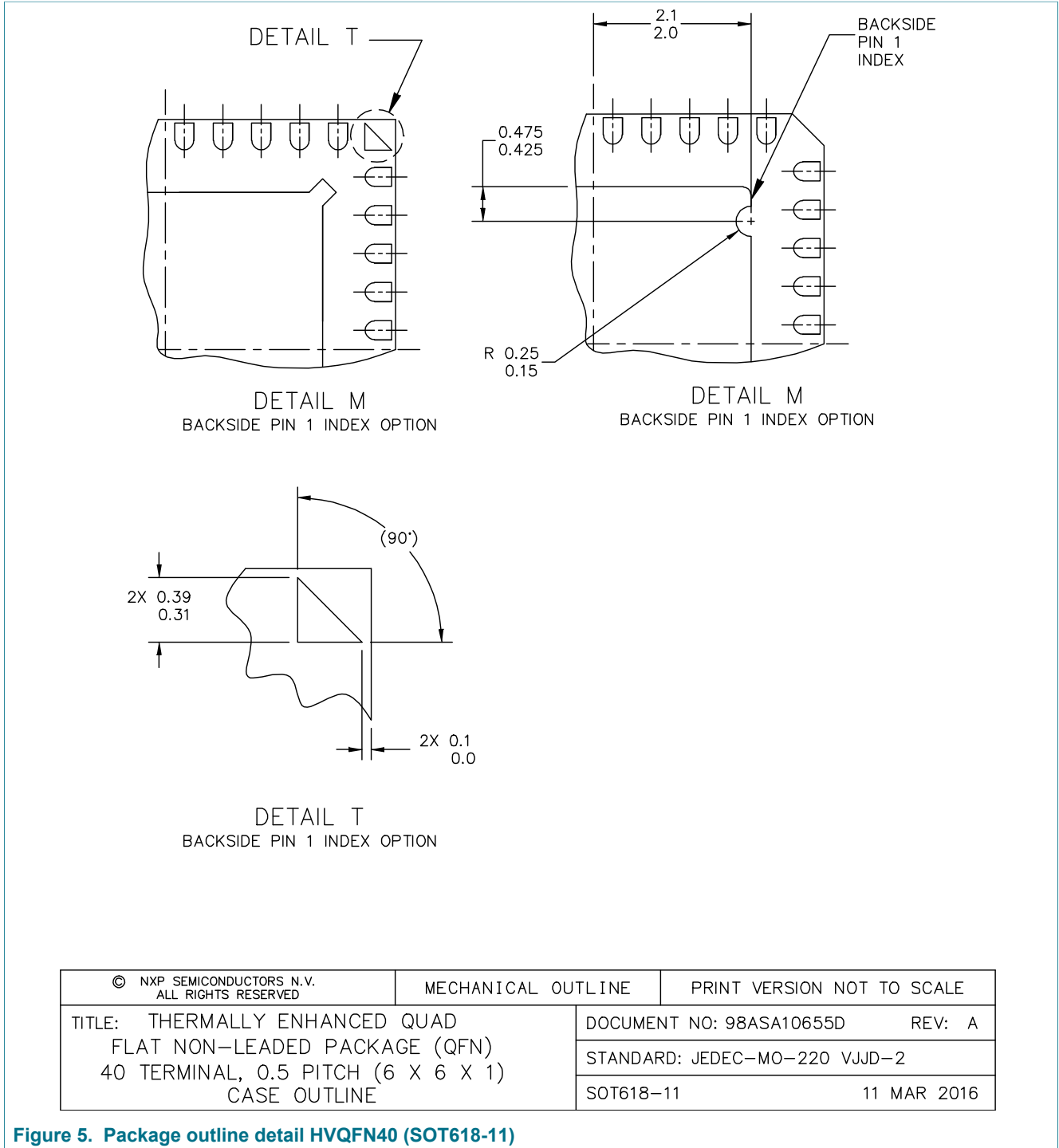




Figure 5. Package outline detail HVQFN40 (SOT618-11)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  CORNER CHAMFER MAY NOT BE PRESENT. DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
5.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
6. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
7. MINIMUM METAL GAP 0.2 MM.

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 40 TERMINAL, 0.5 PITCH (6 X 6 X 1) CASE OUTLINE	DOCUMENT NO: 98ASA10655D	REV: A
	STANDARD: JEDEC-MO-220 VJJD-2	
	SOT618-11	11 MAR 2016

Figure 6. Package outline note HVQFN40 (SOT618-11)

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3 Legal information

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